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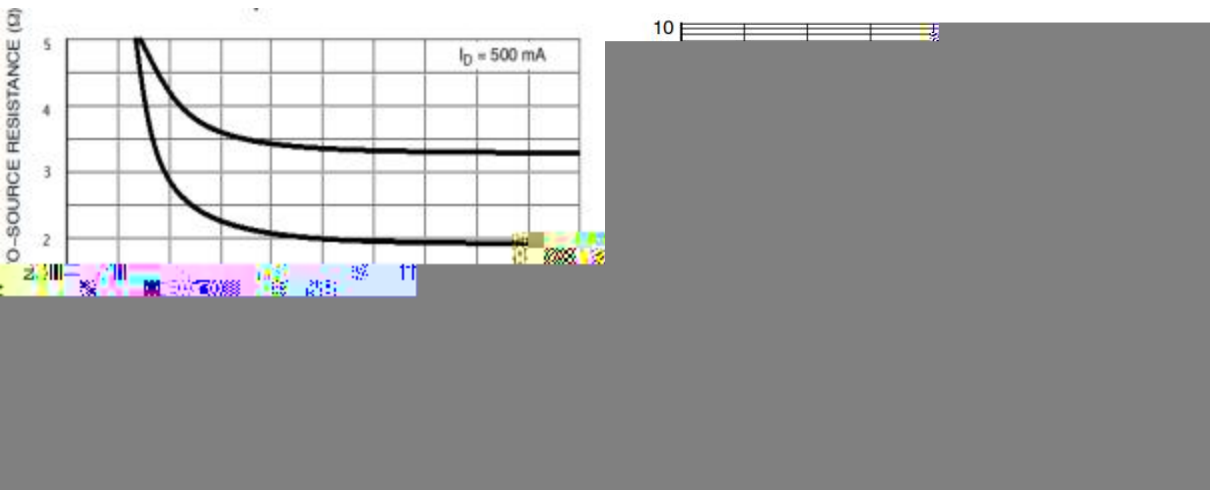
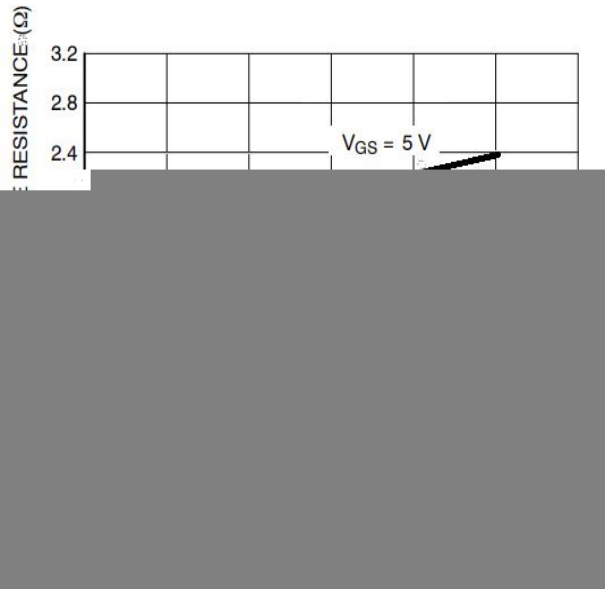
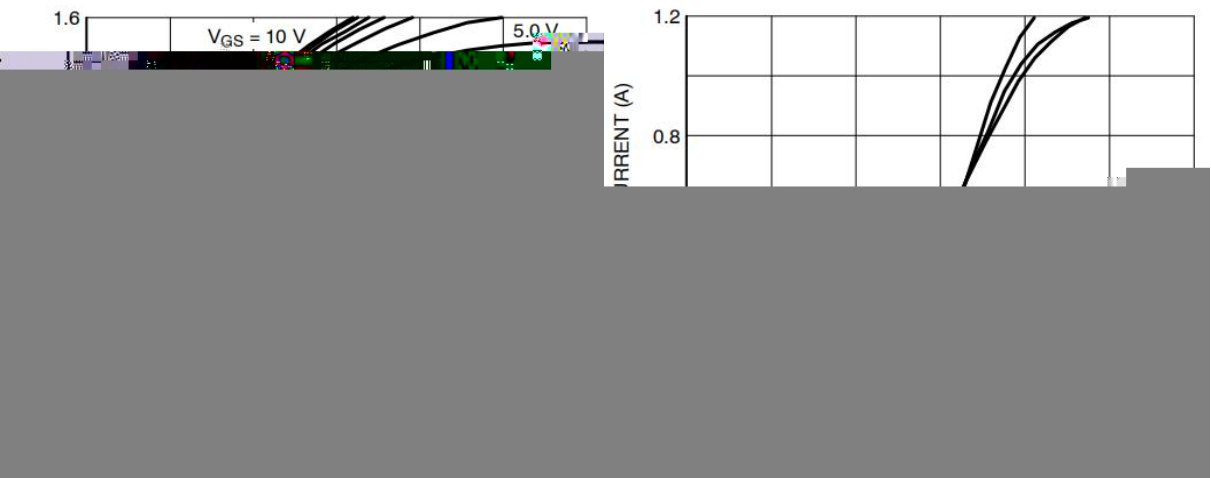
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DATA SHEET

Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
Turn-On Delay Time	$t_{d(ON)}$			12.2		
Rise Time	t	VGS =10V, VDD=25V, ID=500mA, RG=25 Ω				ns

/ Electrical Characteristic Curve



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DATA SHEET

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() / Temperature Profile for IR Reflow Soldering(Pb-Free)

- 说明：
- 1、预热温度 150 ~ 200 , 时间 60 ~ 120sec;

2、峰值温度 255 ± 5 , 时间持续 5 ~ 0.5sec;

3、焊接制程冷却速度为 2 ~ 1 /sec.
- Notes:

1.Pre heating:150~200 , Time:60~120sec.

2.Peak Temp.:255 ± 5 , Duration:5 ~ 0.5sec.

3.Cooling Speed:2 ~ 1 /sec.

/ Resistance to Soldering Heat Test Conditions

温度：260 ± 5